

# *Vacuum System Upgrade*

Y.Suetsugu, KEKB Vacuum Group

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1. Basic Design
  - 1.1 Beam Chambers: *Ante-chamber Scheme*
  - 1.2 Pumps: *Pump, Pressure, Vacuum Scrubbing*
  - 1.3 Connections: *Flange+Bellows*
  - 1.4 Special Components: *Movable Masks, HOM Dampers*
2. R&D Status: *Ante-chamber, Bellows, Masks*
3. Summary

# 1. Issues for Vacuum System

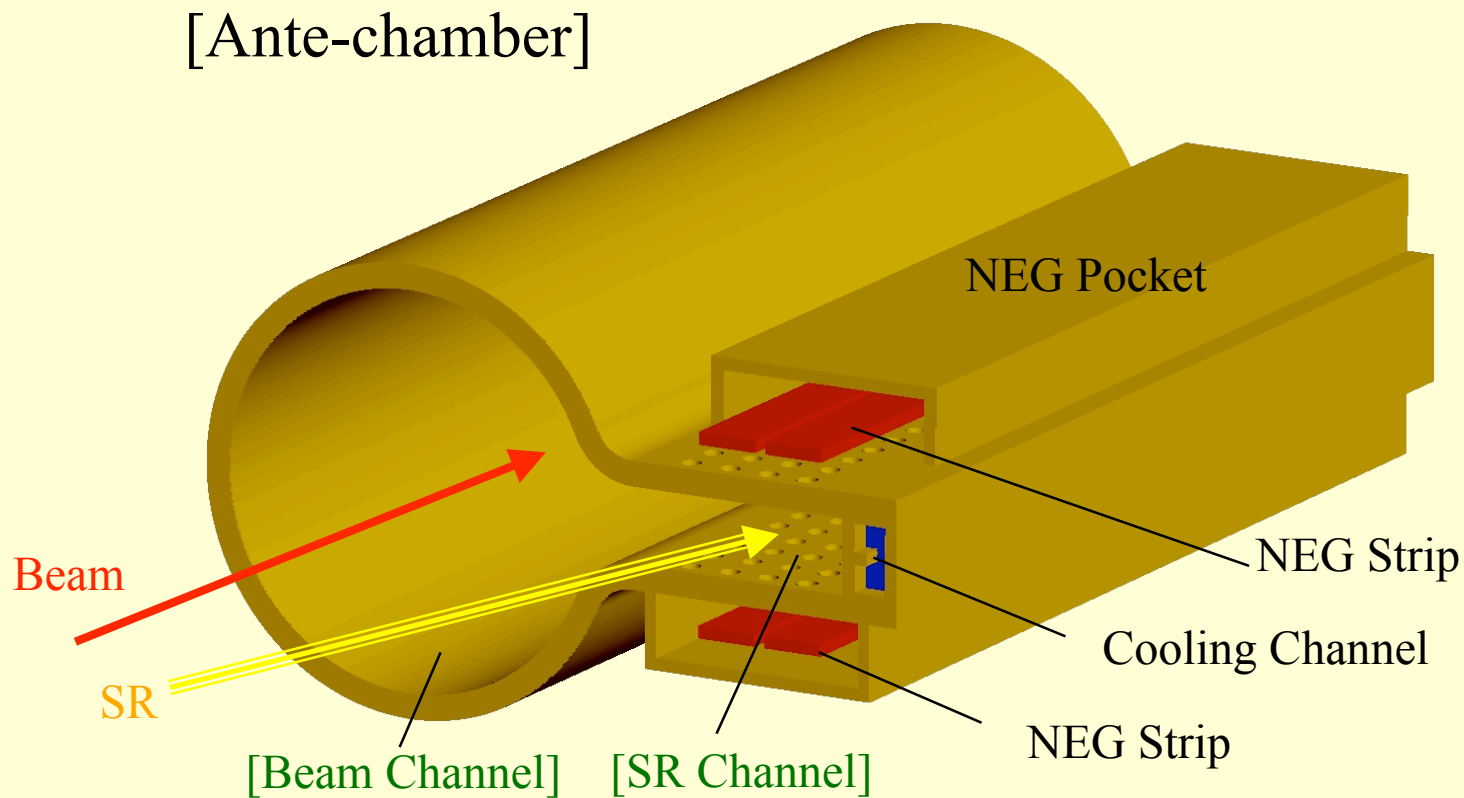
## Parameters Considered Here

	LER	HER
Energy [GeV]	3.5	8.0
Beam Current [A]	9.4	4.1
Bunch Length [mm]	3	3
Bunch Number	5018	5018
Bending Radius [m]	16.31	104.46

- Key points in designing beam chambers and components
  - How to deal with intense SR?
  - How to reduce beam impedance?

# 1.1 Beam Chamber\_1

- Beam chamber ➡ Ante-chamber scheme



# 1.1 Beam Chamber\_2

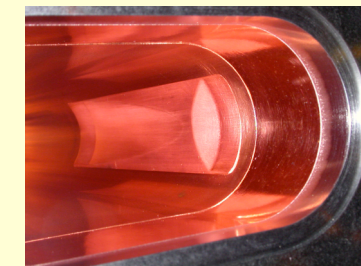
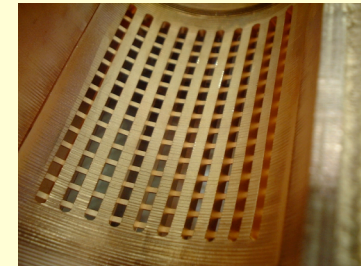
## Merits of Ante-Chamber

### (1) Low power density of SR

- For LER,  $134 \text{ W mm}^{-2}$  ( $h_a = 47 \text{ mm}$ ) [Max.475 °C]  
[9.4 A]  $\Rightarrow 39 \text{ W mm}^{-2}$  ( $h_a = 112 \text{ mm}$ ) [Max.156 °C]

### (2) Low Impedance

- 1 pumping port of KEKB ( $\phi 94$ ):  $k = 6 \times 10^7 \text{ V C}^{-1}$   
 $\Rightarrow k = 9 \times 10^5 \text{ V C}^{-1}$  per 1 m ( $\sim 1/100$ )
- SR mask of KEKB (5mm height):  $k = \sim 5 \times 10^9 \text{ V C}^{-1}$   
 $\Rightarrow k = 1 \times 10^5 \text{ V C}^{-1}$  per 1 m ( $\sim 1/10000$ )

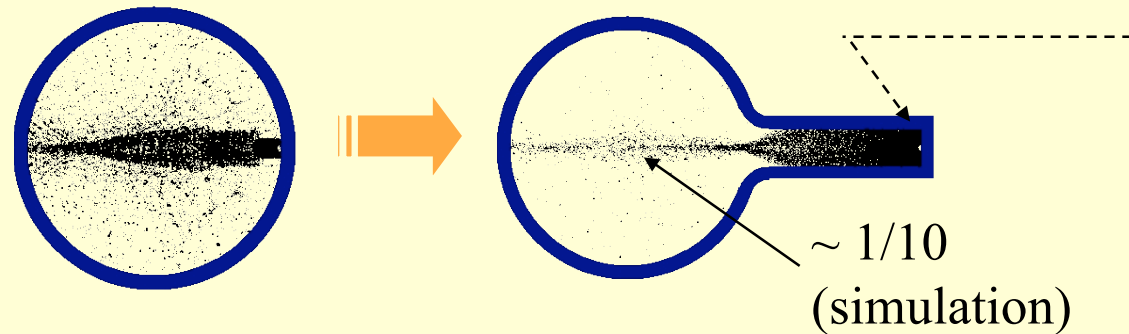


# 1.1 Beam Chamber\_3

- Merits of Ante-Chamber (positron ring)

- (3) Less photoelectrons in beam channel

- Not perfect

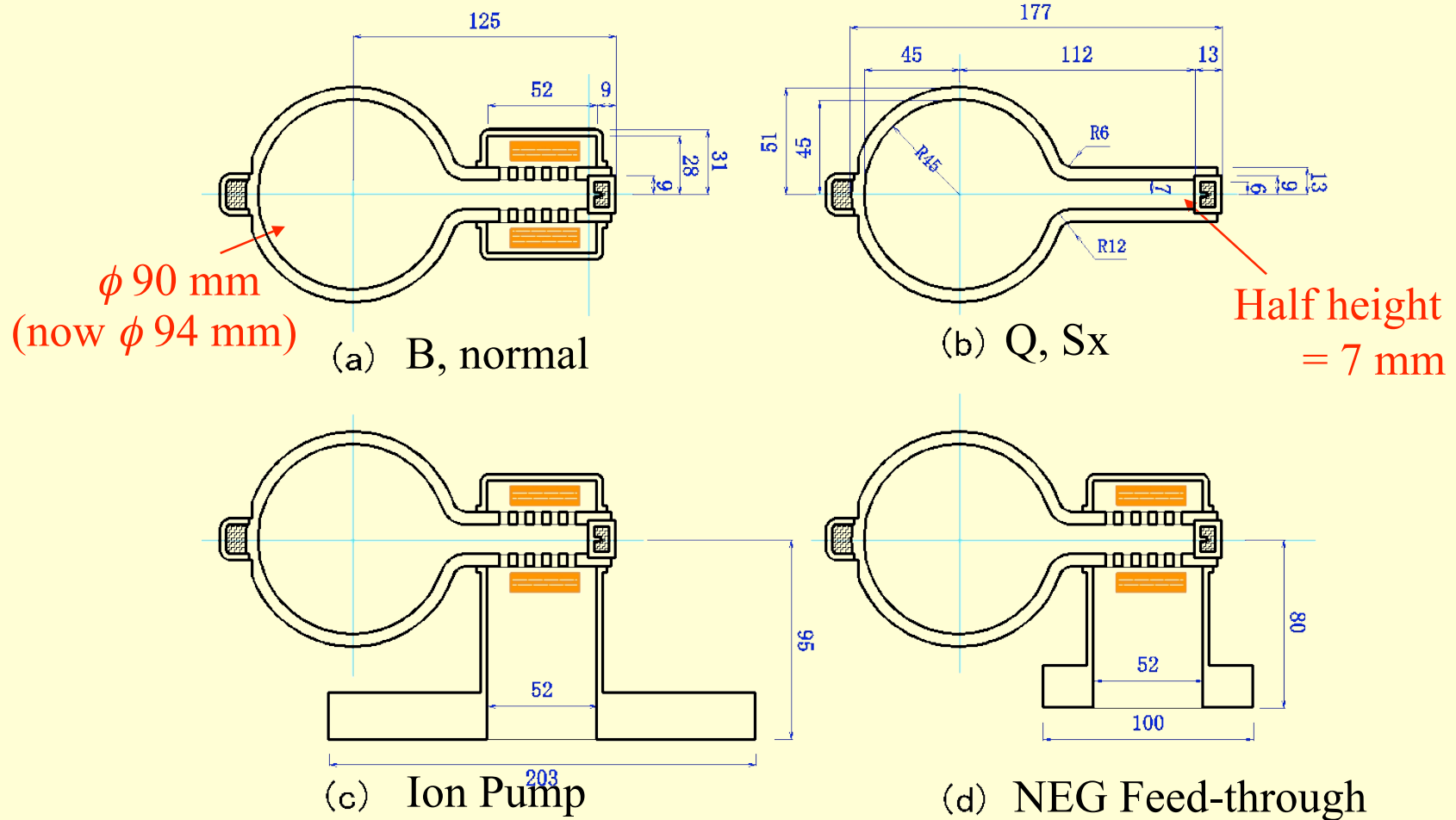


- (4) Low photoelectron yield by using a rough surface on side wall (< 1/10)

- Rough surface at far side wall has little effect on beam.
    - Reflection of SR is also reduced by a rough surface.

# 1.1 Beam Chamber\_4

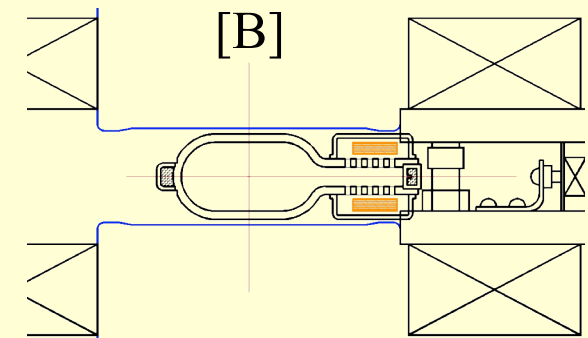
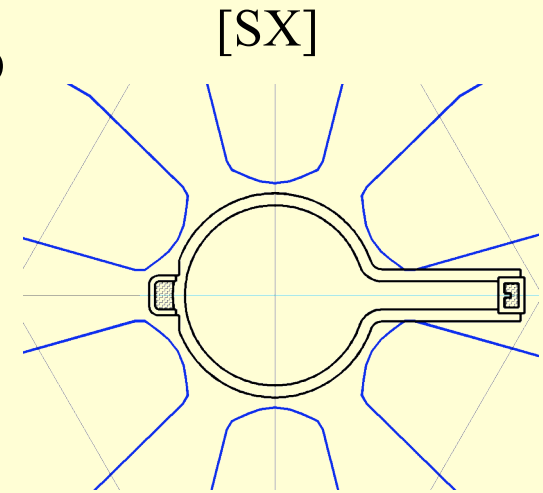
## ● Cross Sections - LER





# 1.1 Beam Chamber\_6

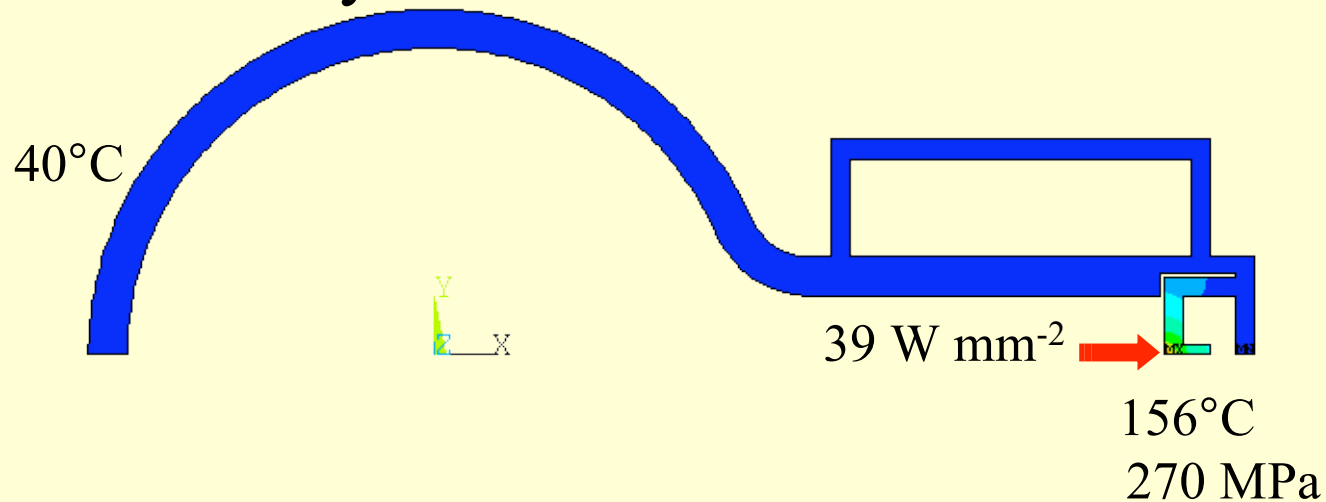
- Large sizes of beam chamber is better,
  - Decrease SR heat load
  - Increase conductance, capacity of pump
- But the sizes are limited by magnets
  - **Q, SX:**
    - Half aperture, Diameter
    - Height of SR channel
  - **B:**
    - Height of NEG pocket (for HER)



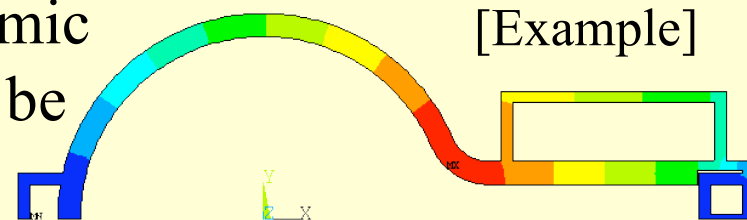


# 1.1 Beam Chamber\_7

- Thermal analysis

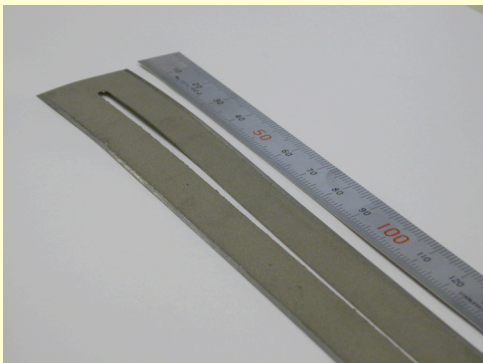


- Considering HOM power or ohmic loss, extra cooling channel will be required



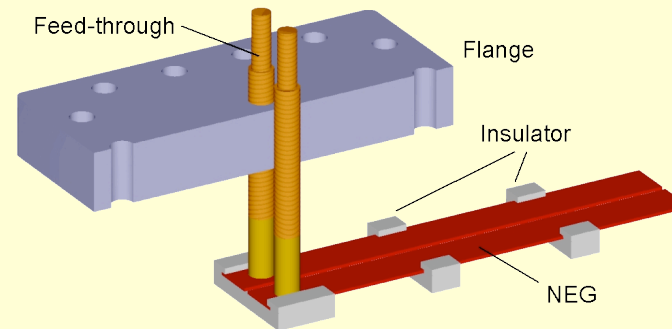
# 1.2 Pumping\_1

- Goal Pressure :  $5 \times 10^{-7}$  Pa in average
  - Beam life time  $\sim 10$  hours (Luminosity life time  $\sim 2$  hour)
  - Necessary pumping speed =  $0.1 \text{ m}^3 \text{ s}^{-1} \text{ m}^{-1}$   
(for  $\eta = 1 \times 10^{-6} \text{ mol. Photon}^{-1}$ )
- Pumps : **Distributed Pumping Scheme**
  - **NEG strip** (+ lumped ion pump)



[ST 707 NEG Strip]  
(30 mm in width)

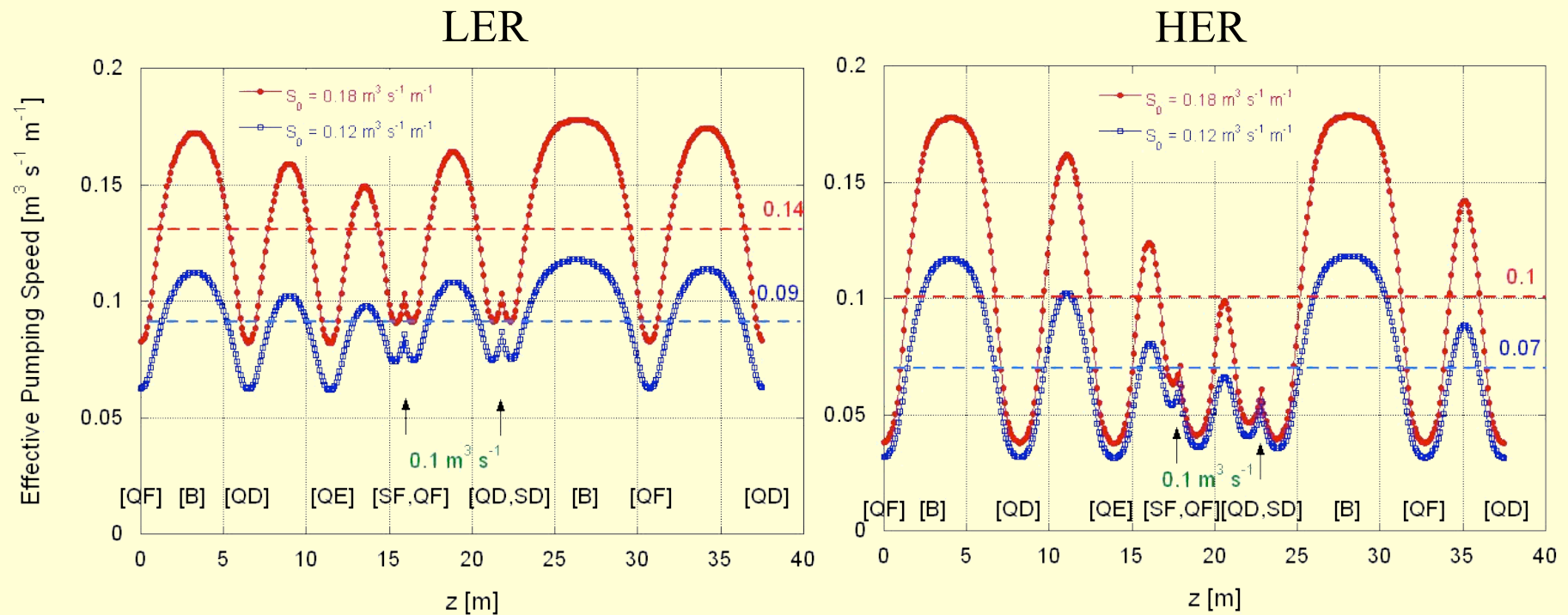
[Feed-trough for NEG activation]



# 1.2 Pumping\_2

## Estimation of Pumping Speed

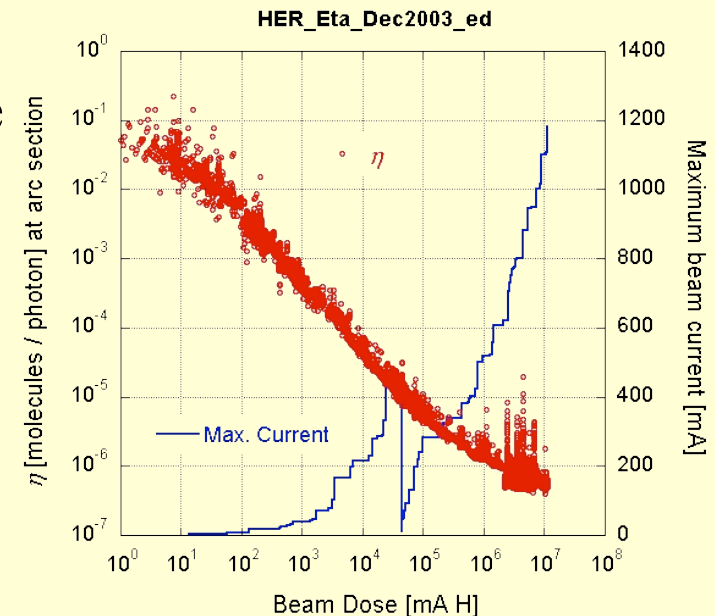
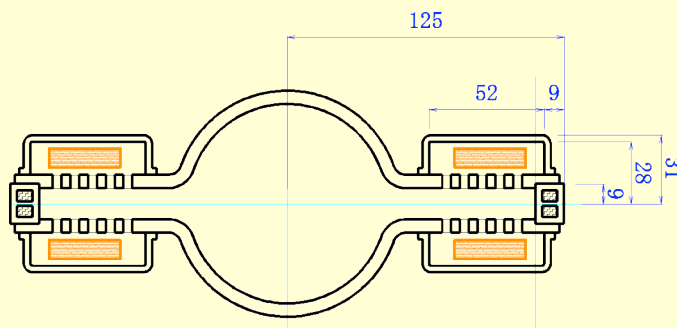
- NEG: 2.0 (1.25)  $\text{m}^3 \text{s}^{-1} \text{m}^{-2}$  (after some saturation)
- Lumped pumps between adjacent Q and Sx ( $0.1 \text{ m}^3 \text{ s}^{-1}$ )



# 1.2 Pumping\_3

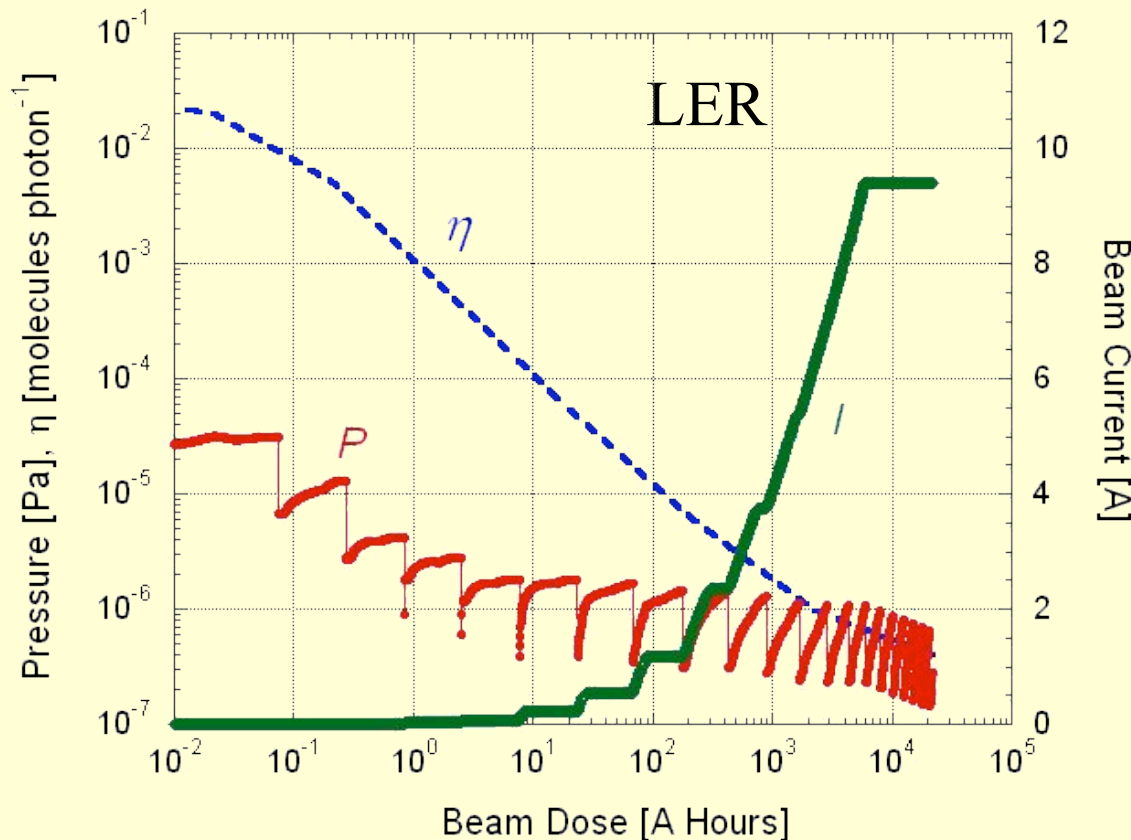
- For more pumping speed
  - Double NEG strip as for chambers at Wiggler section
  - Put more lumped pumps near Q and Sx
  - Enlarge bore size of magnets and put pumps in magnets (?)
- Assumption of  $\eta = 5 \times 10^{-7}$  molecules photon<sup>-1</sup> may be reasonable nowadays
  - $\eta = 1 \times 10^{-6}$  may be conservative

[Example at wiggler section]



# 1.2 Pumping\_4

## Vacuum Scrubbing (simulation)



### Assumption

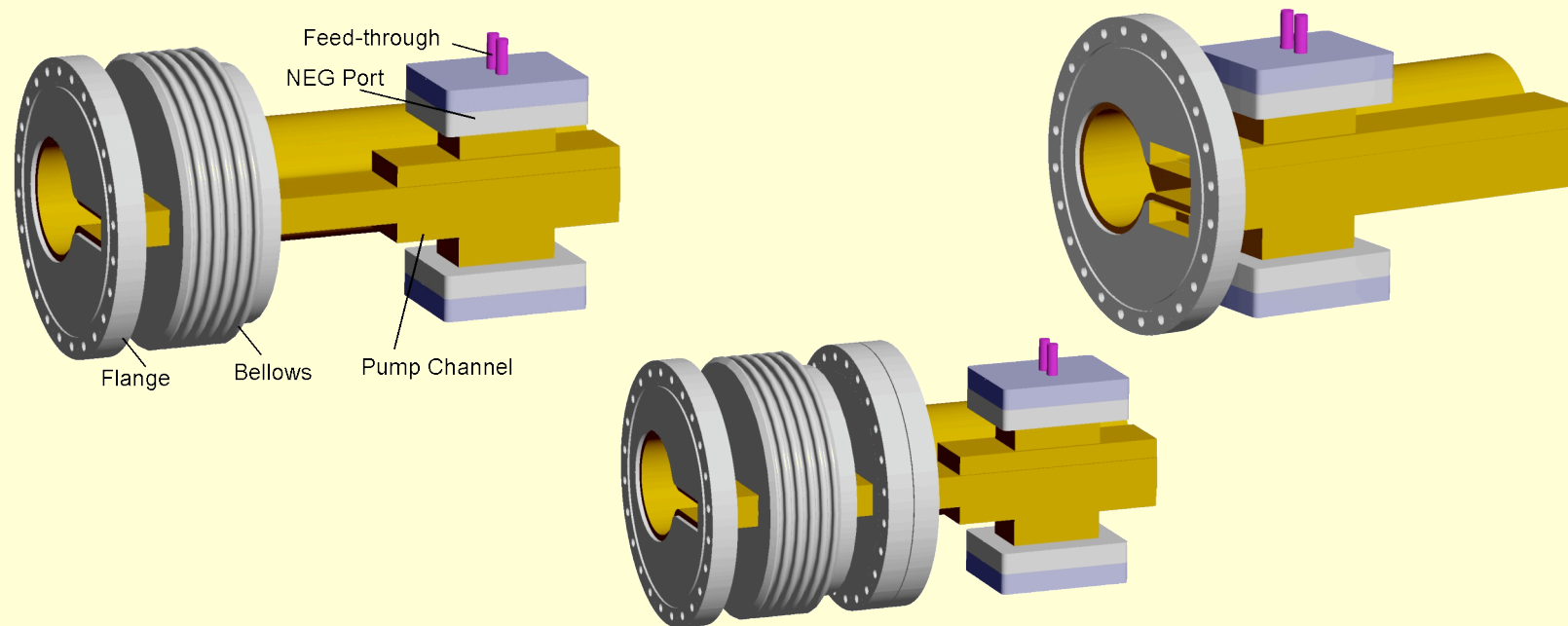
- $\eta$  : Based on KEKB
- $I$  : Increases gradually (18.8 mA step when  $\tau > 5$  hours) ( $\tau$  : Brems., CO)
- NEG : Activate when  $S < 0.02 \text{ m}^{-3} \text{ s}^{-1} \text{ m}^{-1}$

Activation  $> 20$

Need more capacity of NEG

# 1.3 Connection\_1

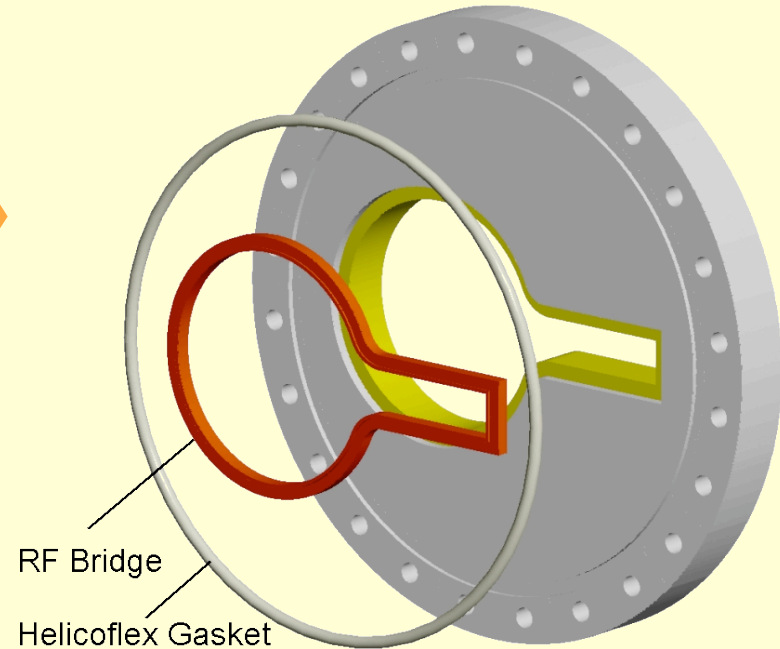
- Use flange + bellows to connect chambers
  - Make handling of beam chambers easy by using bellows and flanges
  - Several configurations are under consideration



# 1.3 Connection\_2

## Flange

- Use special RF-bridge and Helico-flex
- Or develop a special gasket that doubles as vacuum seal and RF shield



Common Problem:

How to absorb tilt between adjacent chambers

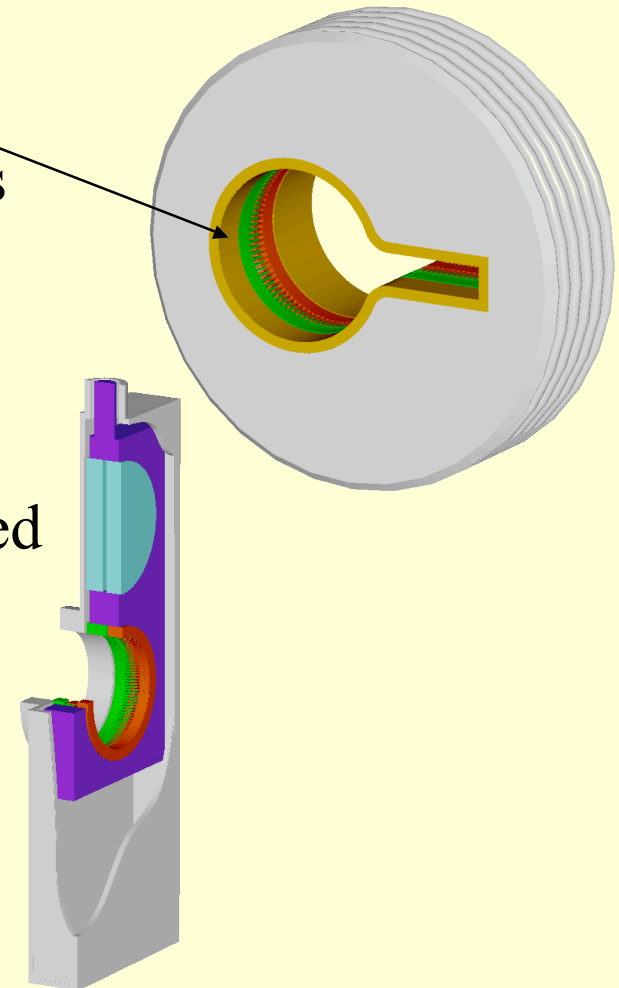
# 1.3 Connection\_3

## • Bellows

- With new or improved RF shield to avoid HOM heating (see R&D)
- Position feed back system for BPM is unnecessary

## • Gate valves

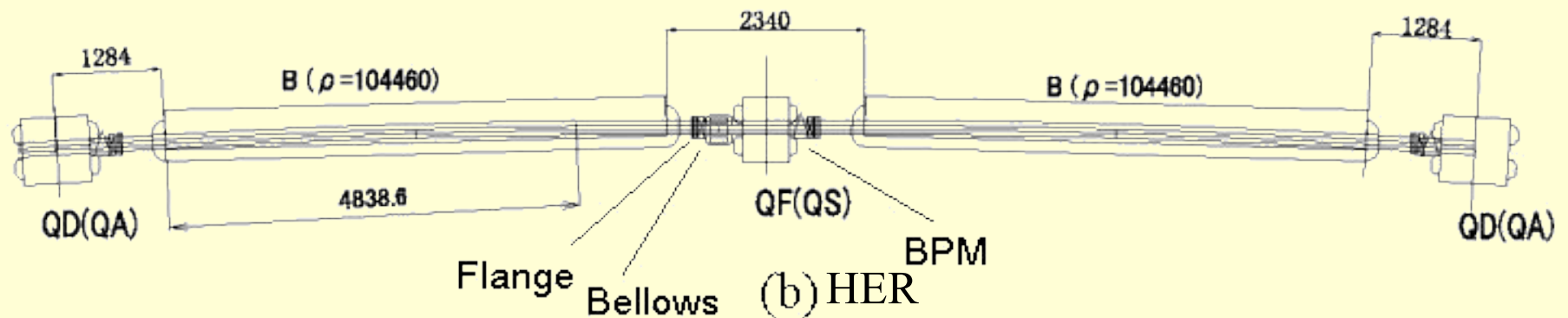
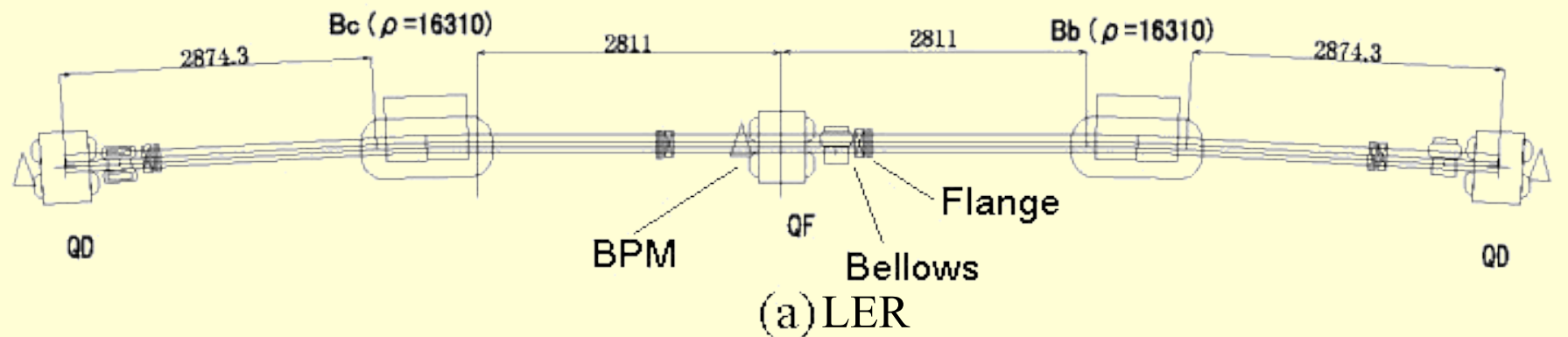
- Same problem with bellows
- New or improved RF shield is required
- Ante-chamber cross section ?
  - Tapers at both sides





# 1.3 Connection\_4

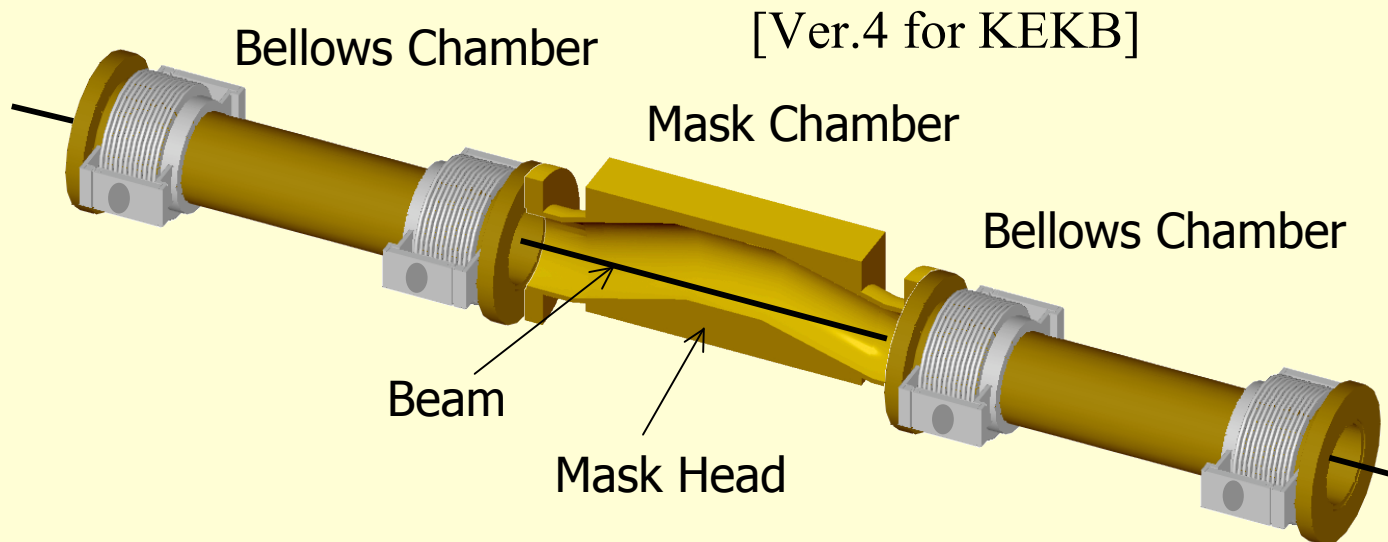
- General Layout (two bellows between Q magnets)



# 1.4 Special Components\_1

## ● Movable Mask

- Necessary to reduce background of detector
- Basically the same structure with present type
- Material of head : C or Be ?



# 1.4 Special Components\_2

## Movable Mask

Problem : High Impedance

$k = 1 \text{ V pC}^{-1}$

@  $\sigma_z = 3 \text{ mm}$



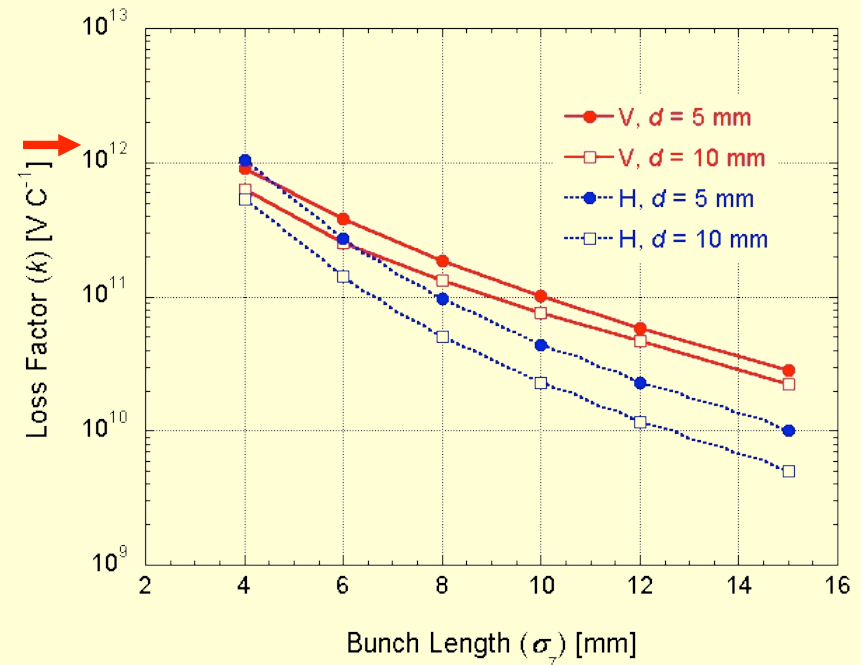
Loss  $\sim 200 \text{ kW} !!$

@5000 bunches and 9.4 A

Reduce number ?

Powerful HOM absorber ??

[Calculated loss factor]

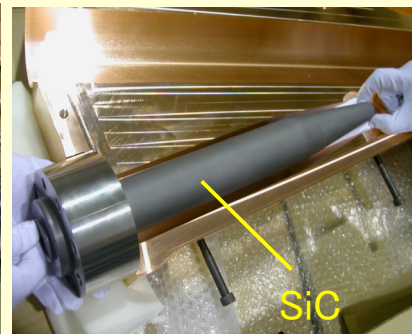
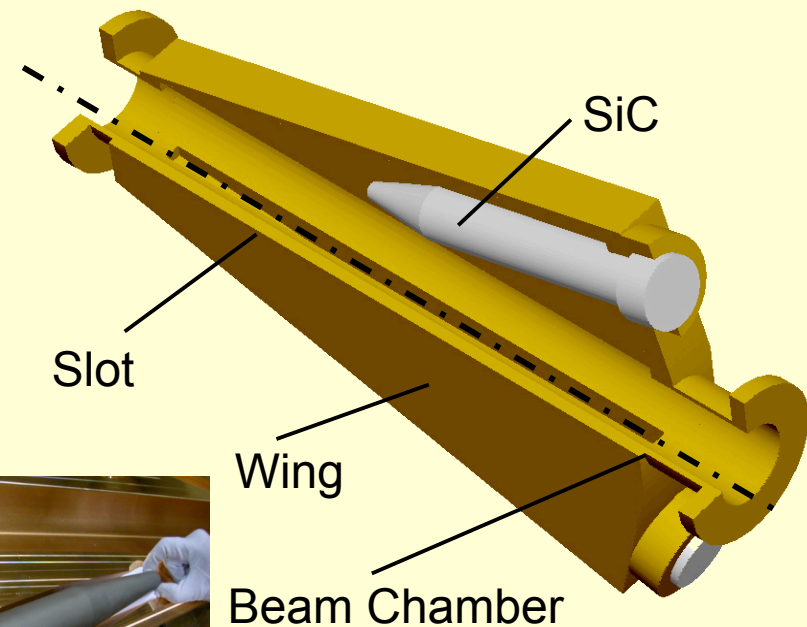


# 1.4 Special Components\_3

- HOM absorbers for various components

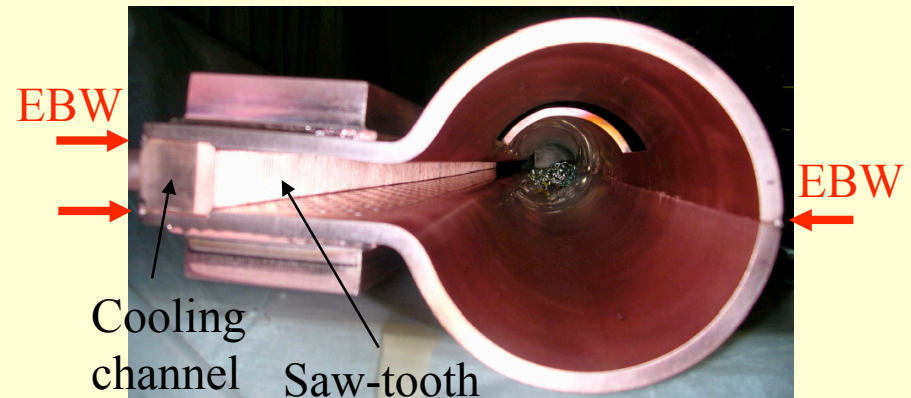
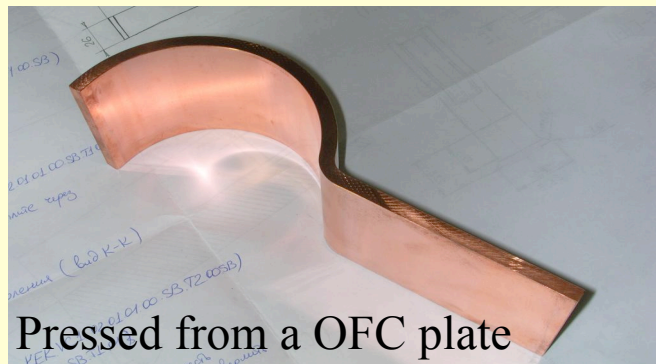
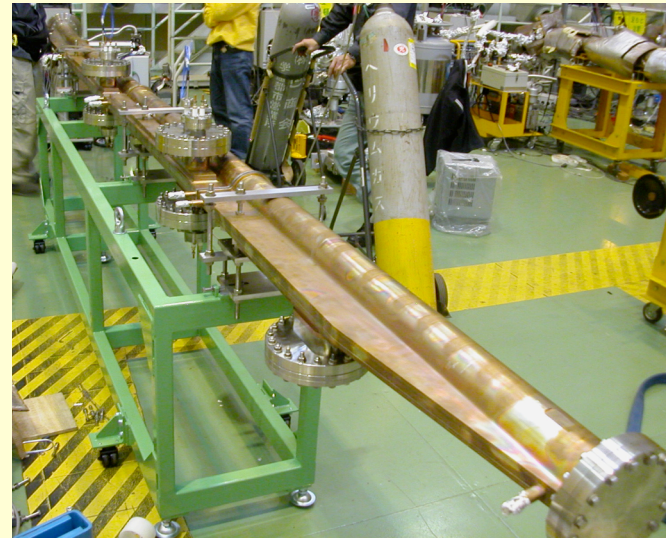
- Become more and more important components
- More powerful absorber is required

[HOM absorber for KEKB movable masks]



## 2. R&D Status\_1

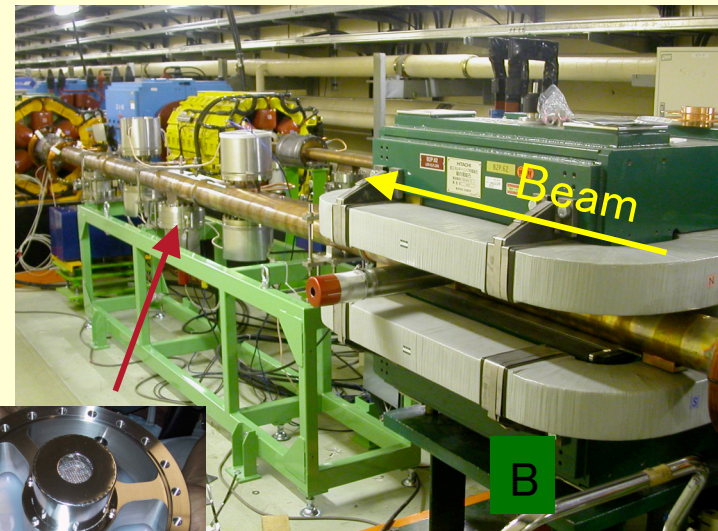
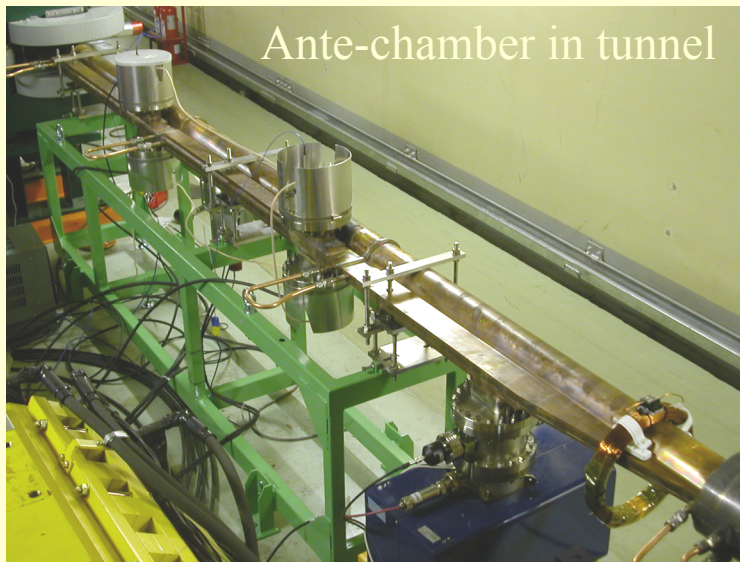
- Ante-Chamber\_Type-1
  - Length: 5.2 m
  - Manufactured in BINP
  - Material : Copper (OFC)
  - Forming : **Stamp**
  - Welding : EBW
  - Saw-tooth at side wall



## 2. R&D Status\_2

### ● Ante-Chamber\_Type-1

- Installed in LER last month
- Electrons in beam channel and temperatures of chambers were measured

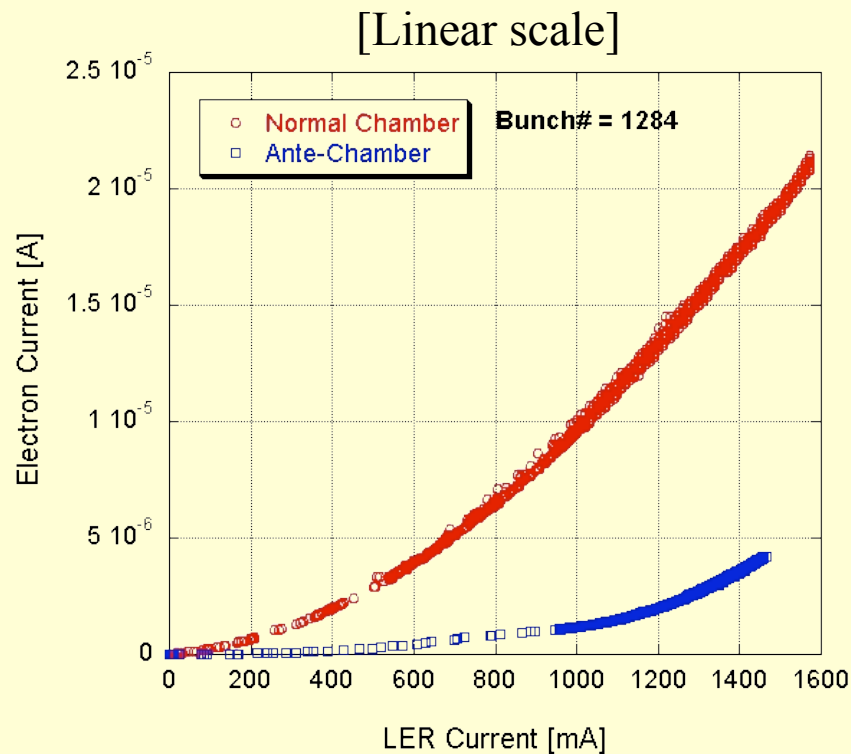


Electron Monitor  
(DC, +100 V)

## 2. R&D Status\_3

### Ante-Chamber\_Type-1

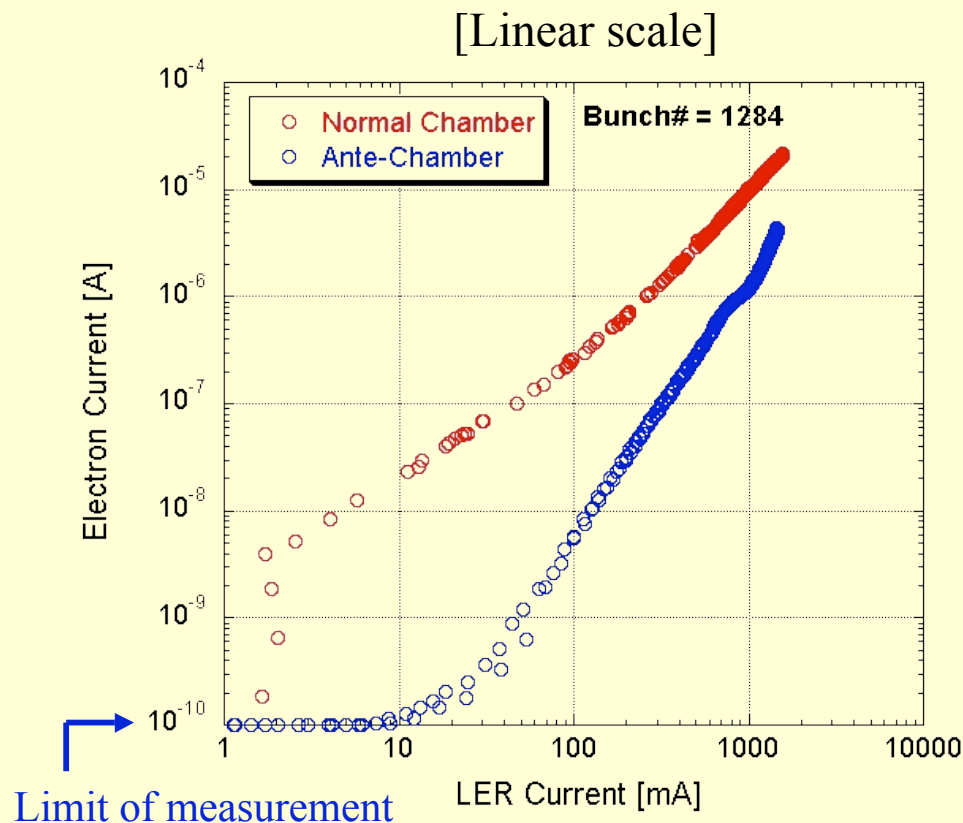
- First result of electron measurement (without solenoid)



- Measured in DC mode (average)
- Bias voltage = 100 V
- Non-linear dependence on beam current  
Multi-pactoring
- Electron current for ante-chamber is smaller than that for normal chamber.
- Reduction rate is about 1/4 at 1.4 A

## 2. R&D Status\_4

### First result



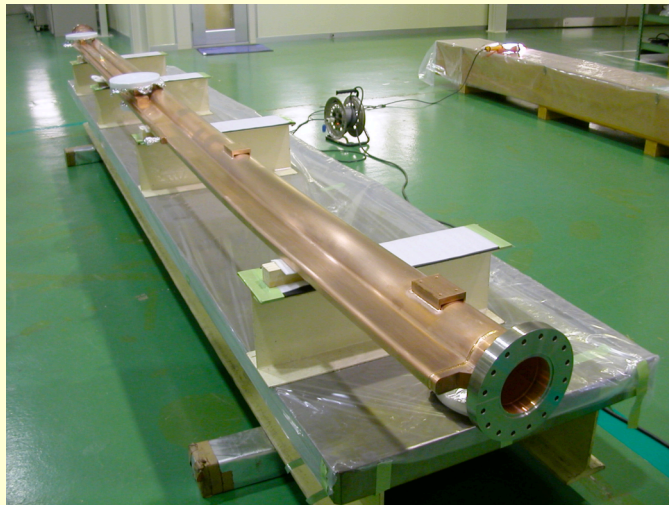
- Normal chamber:  
Photoelectrons are dominant
- Ante-Chamber:  
Multiplied second electrons are dominant
- Reduction rate is about 1/4 at 1.4 A, but 1/300 at 20 mA
- Almost in agreement with expectation:
  - Ante-chamber: ~1/10
  - Saw-tooth: ~1/20
- Ante-chamber is insufficient to suppress multiplication of secondary electrons at high current.
  - Solenoid, Surface treatment ?
  - Need further investigation



## 2. R&D Status\_5

### ● Ante-Chamber\_Type-2

- Under manufacturing : Almost same structure with Type-1
- Material : Copper (OFC)
- Forming : **Drawing**
- Welding : EBW



[Drawn pipe]



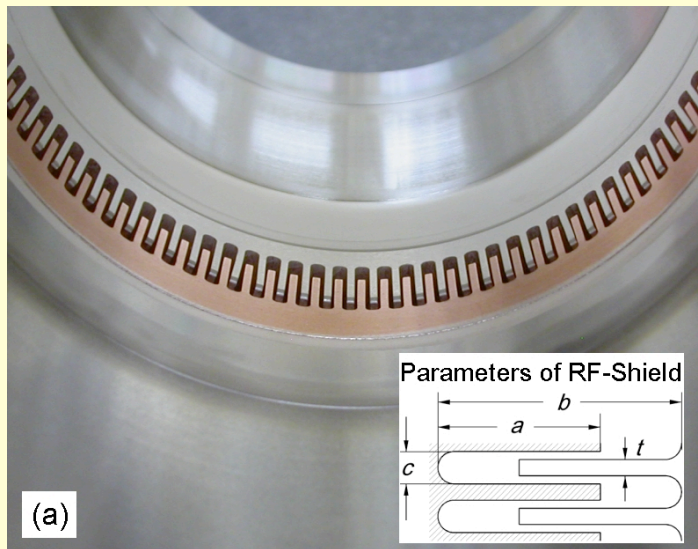
- Experiments and studies are under going

## 2. R&D Status\_6

- Bellows (RF Shield)

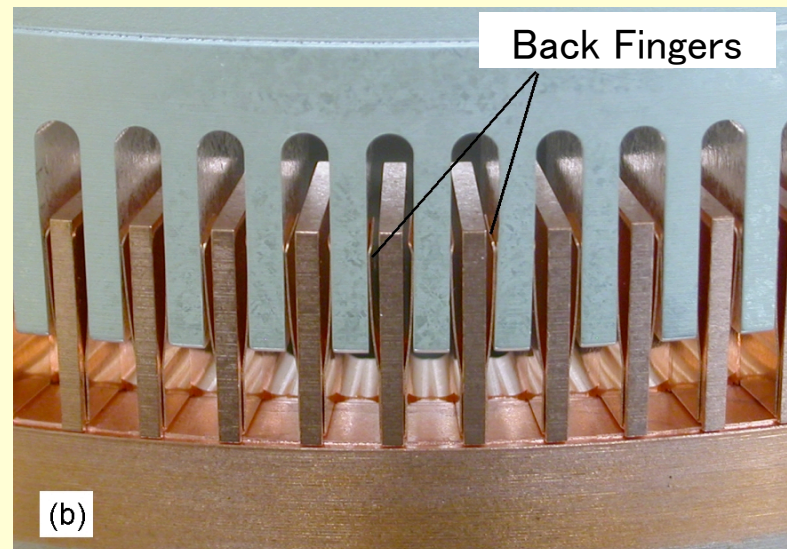
- Comb-type RF Shield

- High thermal strength, Low impedance



Inside view

$a = 10$  mm,  $b = 15$  mm,  $c = 2$  mm

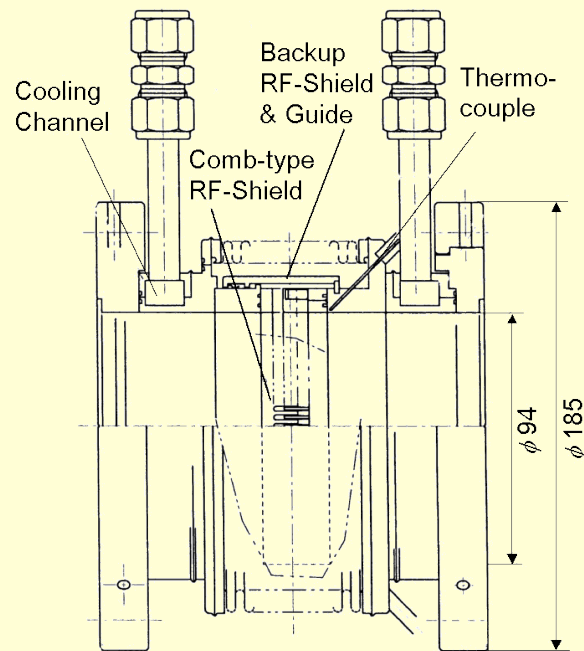


Outside view

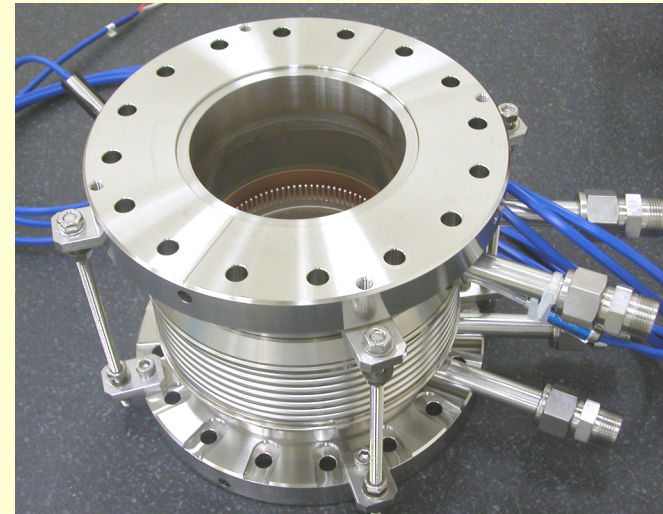
## 2. R&D Status\_7

### ● Bellows with comb-type RF Shield

- Two trial models were installed in LER last summer at downstream side of movable masks (most severe location)
- Temperatures of corrugation and comb were measured and compared with finger-type bellows at the same location



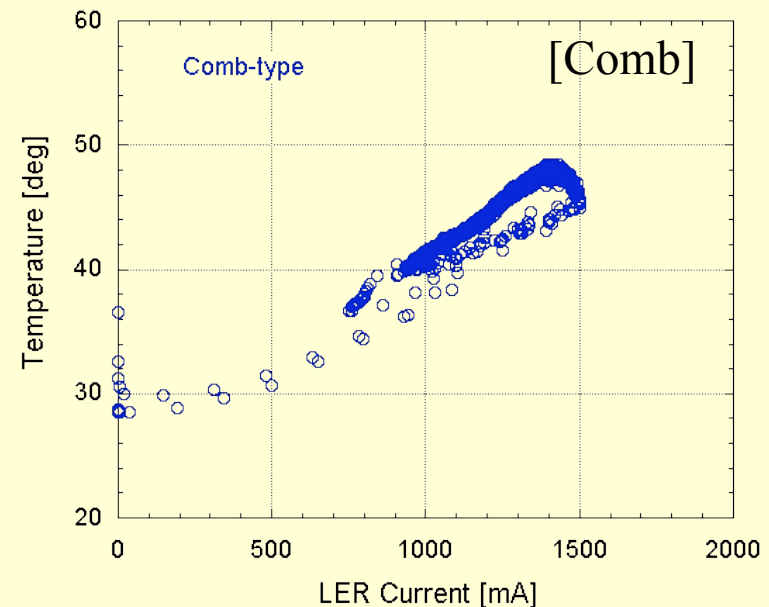
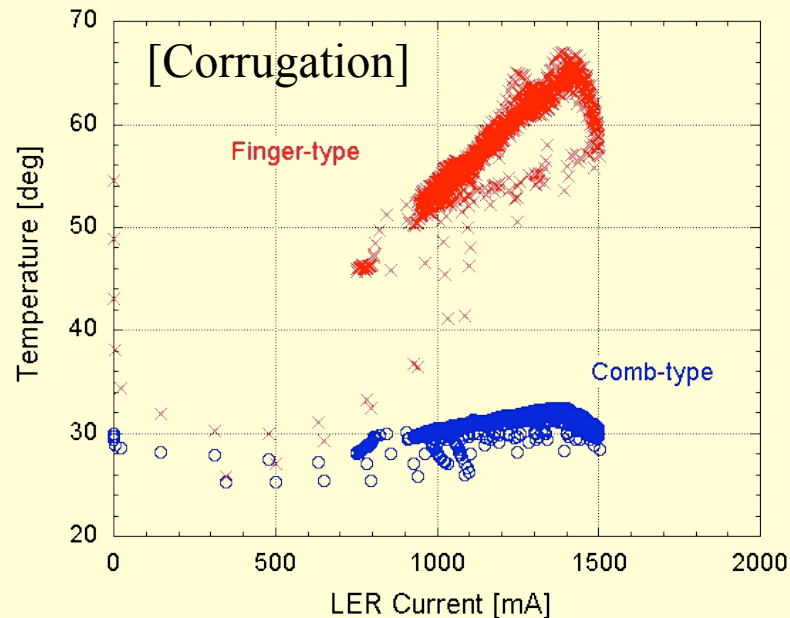
[Trial model]



## 2. R&D Status\_8

### Results of beam test

- Temperature at corrugation reduced to  $\sim 1/6$
- Temperature of comb is about  $50^{\circ}\text{C}$  at 1.5 A, that of finger is estimated to be  $\sim 130^{\circ}\text{C}$  at the same condition.



## 2. R&D Status\_9

- Bellows with comb-type RF Shield
  - Working very well up to 1.5 A
- Problems
  - Small longitudinal movement (+3/- 4 mm at present)
    - ⇒ Control of chamber temperature is required
  - Rather complex structure
- Future plan
  - Application to more small diameter chamber (~48 mm), to a race-track cross section (104×50 mm) and to gate valves
  - Simplify the structure and expand stroke

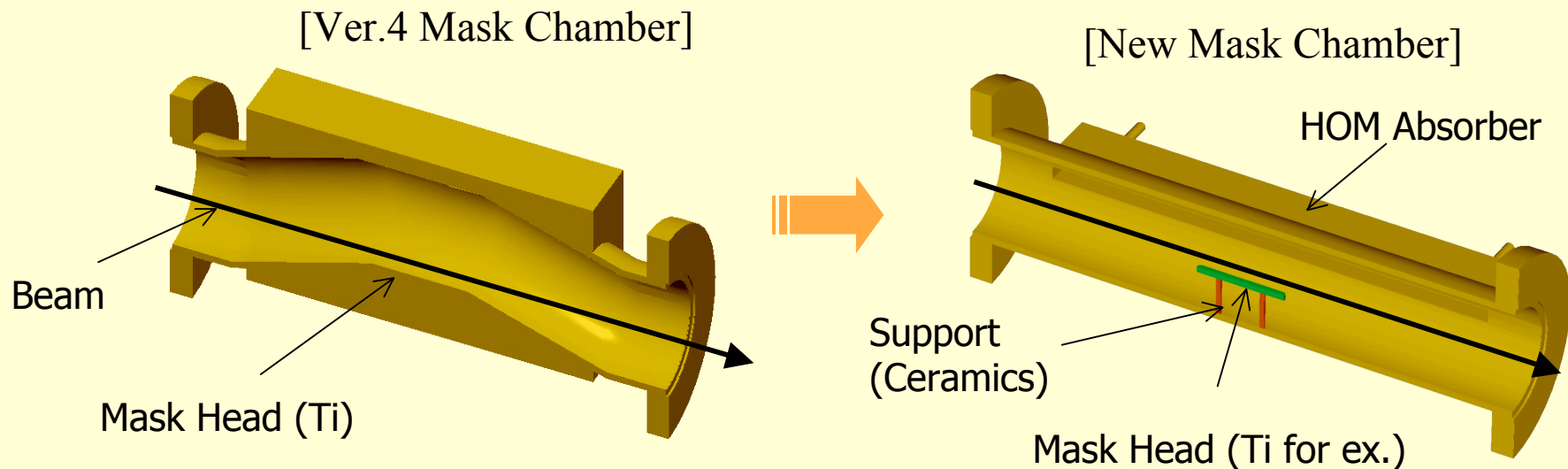
## 2. R&D Status\_10

### Movable Mask

- A big HOM source (200 kW / mask)
- There is a limitation on the present way of thinking (make slopes gentle, for example)

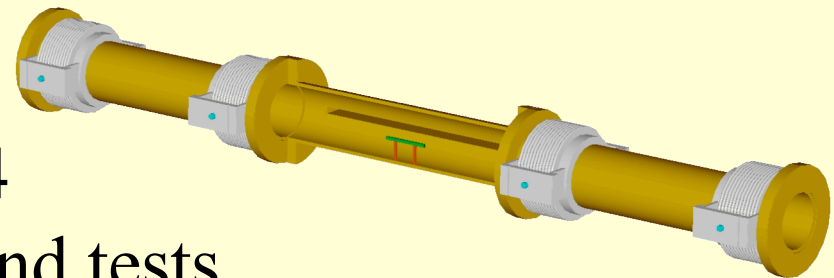
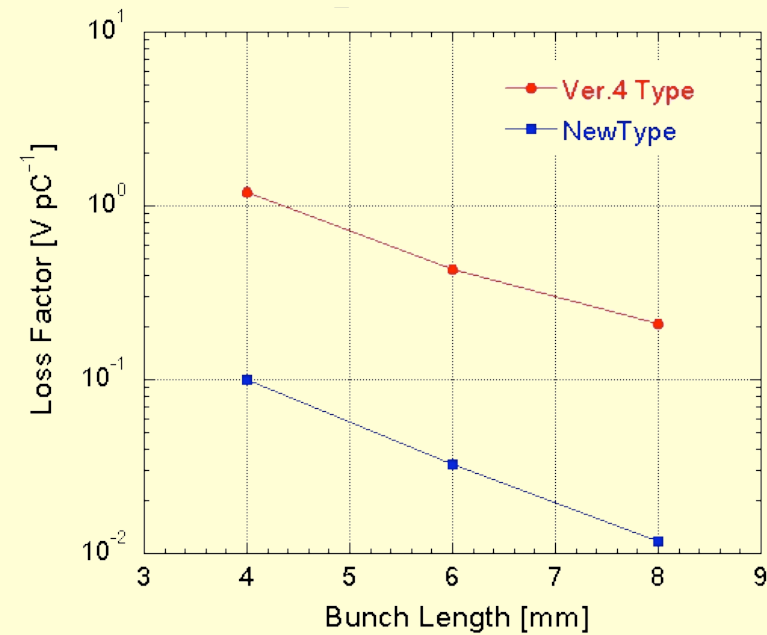
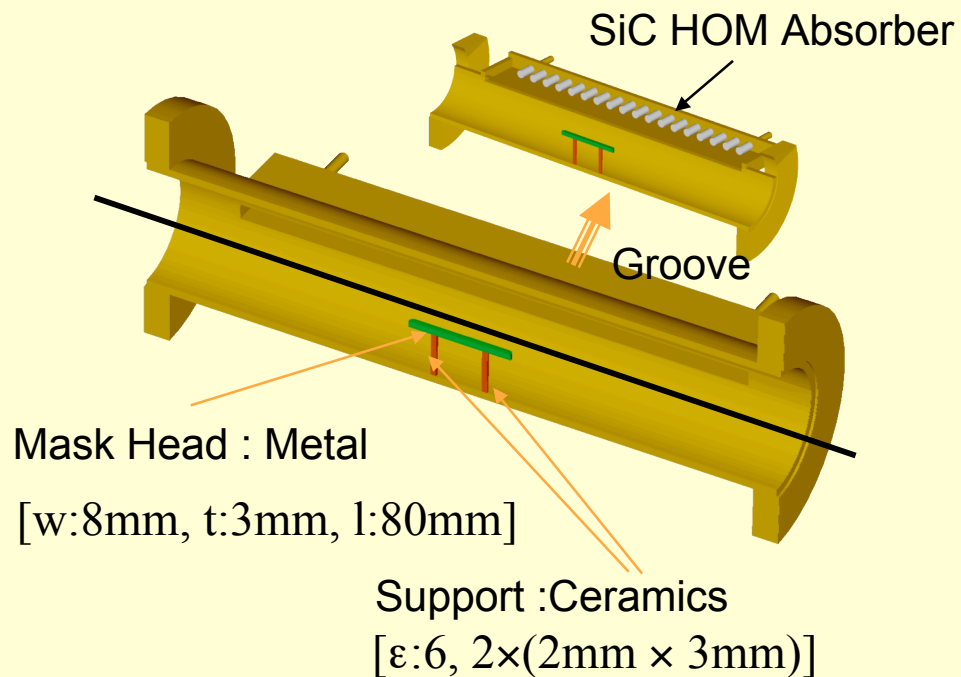
### An idea for mask with lower impedance

- Slender mask head supported by ceramics rods



## 2. R&D Status\_11

- Small loss factor



- Same configuration to Ver.4
- Need further investigation and tests

# 3. Summary

- Basic design of vacuum system is taking shape
  - The design is based on that of KEKB and introducing new ideas at the same time
  - Antechamber scheme is suitable for beam duct
  - Pumps are NEG strips and ion pumps
  - Bellows and flanges are used to connect ducts
  - R&Ds for ante-chamber, RF-shield, flange and movable masks are undergoing
- Remained issues
  - How to suppress electron multipactoring
    - Solenoid (+ coating ?), How is inside of Q or Sx?
  - Design of straight sections, IR